EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	5712	438/106	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2007/11/26 10:29
L2	1124	438/121	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2007/11/26 10:31
L3	2007	438/125	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2007/11/26 10:32
L4	1367	438/122	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2007/11/26 10:33
L5	3177	438/118	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2007/11/26 10:35
L6	989	438/119	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2007/11/26 10:38
L7	3454	(257/678).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2007/11/26 10:42
L8	575	(257/702).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2007/11/26 10:50

L9	1525	(257/704).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2007/11/26 10:50
L10	1800	(257/706).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2007/11/26 10:52
L11	2878	(257/712).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2007/11/26 10:53
L12	1198	(257/717).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2007/11/26 10:56
L14	10995	semiconductor adj chip and molding	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/11/26 11:17
L15	1851	(spacer or standoff or buffer) and 14	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/11/26 11:17
L16	7468	(spacer or standoff or buffer) and method and mounting and exposed and surface.clm.	US-PGPUB	OR	ON	2007/11/26 11:26
L17	783	semiconductor adj chip and 16	US-PGPUB	OR	ON	2007/11/26 11:27
L18	409	(257/e33.058).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2007/11/26 11:29

11/26/07 12:59:29 PM